The Right LDO for Your Application
### Wide Input Voltage

#### Low IQ

- **Powering MCU**
  - **Device**
    - LP5912
    - TPS7A87 (Dual)
    - LP3885x
    - TPS7A88 (Dual)
    - TPS742/3
    - TPS7A83
    - LP3851
    - TPS744
  - **Noise (µVrms)**
    - 0.5
    - 0.8
    - 1.5
    - 3
  - **IQ (µA)**
    - 0.15
    - 0.25
    - 0.3
  - **VDO (mV)**
    - 0
    - 0.5
    - 1
    - 1.5

- **Powering FPGA/DSP (IOUT > 500mA)**
  - **Device**
    - C2000™
    - MSP430™
    - Stellaris®
    - LP2992
    - TPS736
    - TPS735
    - TPS715A
    - TPS7A16
    - LP2936HV
    - TPS7A40
    - TPS780/2
    - TPS706
    - TPS7A7
  - **VOUT (mV)**
    - 0
    - 0.5
    - 1
    - 1.5
  - **IOUT (A)**
    - 2
    - 3
    - 3
    - 4
  - **Vin (V)**
    - 250mA LDO
    - 400mA LDO
    - 500mA LDO
  - **IQ, 24V IN**
    - 5µA
    - 5µA
    - 50V
    - 100V
  - **IQ, 60V IN**
    - 50V
    - 100V
  - **IQ, 50V IN**
    - 5µA
    - 1µA
  - **IQ, 10V IN**
    - 1A

- **Powering Small Package**
  - **Device**
    - TPS7A35
    - TPS7A88 (Dual)
    - TPS7A47
    - TPS7A84/5
    - TPS7A85
    - TPS7A37
  - **VOUT (mV)**
    - 0
    - 0.1
    - 0.2
    - 0.3
  - **IOUT (A)**
    - 0.15
    - 0.25
    - 0.3
    - 0.05
  - **Vin (V)**
    - 0.75
    - 0.15
    - 0.05
    - 0.1
  - **Noise (µVrms)**
    - 3.8
    - 3.8
    - 4.2
    - 4.4

- **Package (mm)**
  - 0.65x0.65 WCSP
  - 0.8x0.8 WCSP
  - 1.3x1 WCSP
  - 1x1 QFN
  - 1.7x1 WCSP
  - 1.5x1.5 DFN
  - 2x2 DFN
  - 2x2 DFN

- **Why?**
  - C2000™
  - MSP430™
  - Stellaris®
Jump start your design process

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